



Material Content Data Sheet



Sales Product Name		TLE4941PLUSC		Issued		28. August 2013		
MA#		MA001039358						
Package		PG-SSO-2-53		Weight*		169.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.368	0.81	0.81	8075	8075
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1702	
	non noble metal	titanium	7440-32-6	0.288	0.17		1702	
	noble metal	silver	7440-22-4	0.384	0.23		2270	
	non noble metal	tin	7440-31-5	0.577	0.34		3405	
	non noble metal	copper	7440-50-8	94.576	55.82	56.73	558386	567465
wire	noble metal	gold	7440-57-5	0.045	0.03	0.03	268	268
encapsulation	organic material	carbon black	1333-86-4	0.578	0.34		3415	
	plastics	epoxy resin	-	10.410	6.15		61463	
	inorganic material	silicondioxide	60676-86-0	46.846	27.66	34.15	276585	341463
leadfinish	non noble metal	tin	7440-31-5	6.247	3.69	3.69	36882	36882
plating	noble metal	silver	7440-22-4	1.029	0.61	0.61	6076	6076
glue	plastics	epoxy resin	-	0.107	0.06		633	
	noble metal	silver	7440-22-4	0.429	0.25	0.31	2533	3166
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		7	
	inorganic material	titandioxide	13463-67-7	0.148	0.09		873	
	inorganic material	leadtitanate	12060-00-3	0.031	0.02		183	
	plastics	epoxy resin	-	0.002	0.00		12	
	inorganic material	bismuth trioxide	1304-76-3	0.255	0.15		1506	
	noble metal	palladium	7440-05-3	0.474	0.28		2799	
	noble metal	silver	7440-22-4	1.499	0.89		8851	
	inorganic material	bariumtitanate	12047-27-7	3.790	2.24	3.67	22374	36605
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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